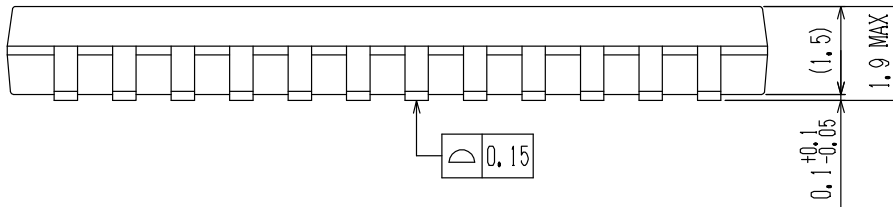
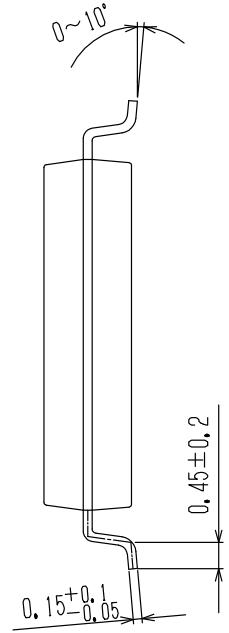
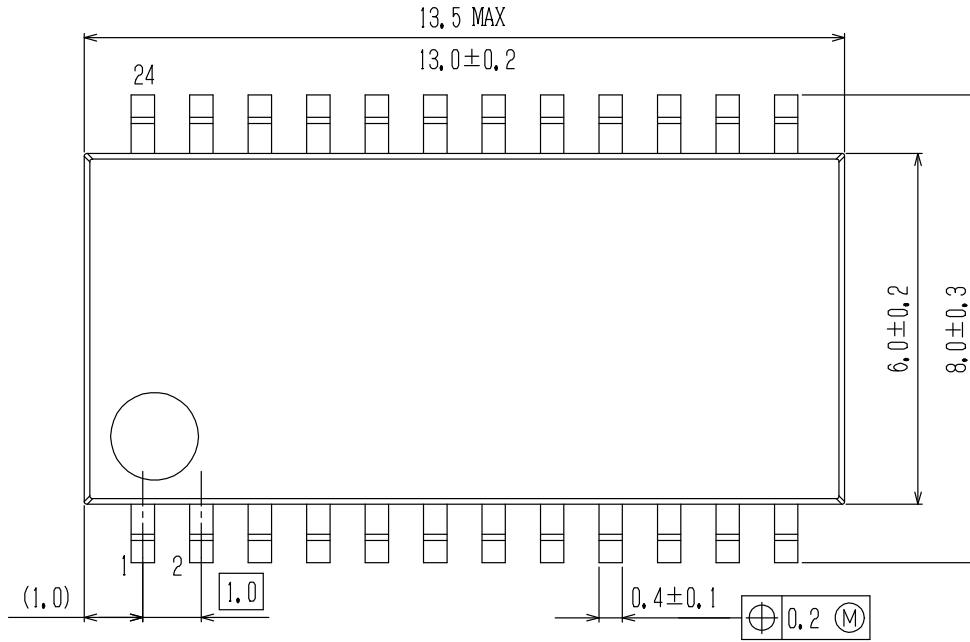
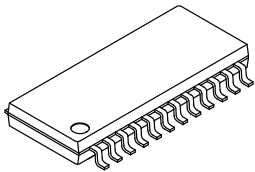


MECHANICAL CASE OUTLINE


PACKAGE DIMENSIONS

SOIC24W / MFP24SJ (300 mil)
CASE 751DB
ISSUE O

DATE 31 MAY 2012



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DESCRIPTION:	SOIC24W / MFP24SJ (300 MIL)	PAGE 1 OF 1

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